



Series LA-B3

## Technical Data

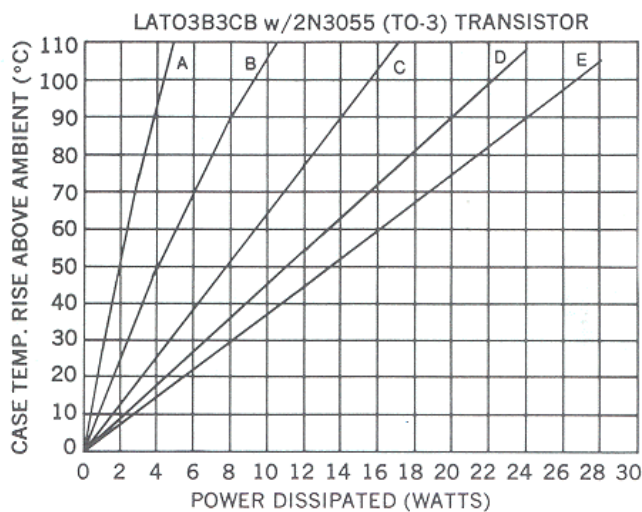
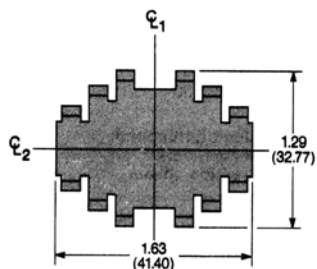
### METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LA-B3

Natural Conv. ( $^{\circ}\text{C/W}$ ): 12

Forced Air ( $^{\circ}\text{C/W}$ ): 3.7

Mounting Envelope: 1.63" x 1.29" x .75"



#### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

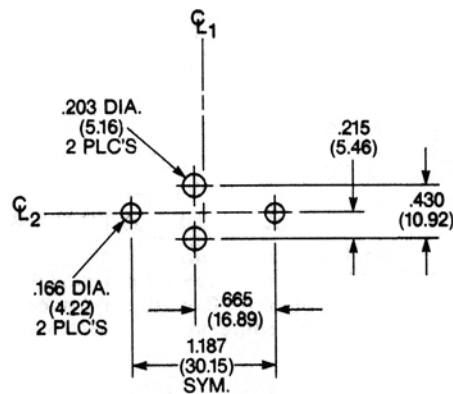
- Thermal Resistance Case to Sink is 0.1-0.3  $^{\circ}\text{C/W}$  w/Joint Compound.
- Derate 0.7  $^{\circ}\text{C/watt}$  for unplated part in natural convection only.

## Ordering Information

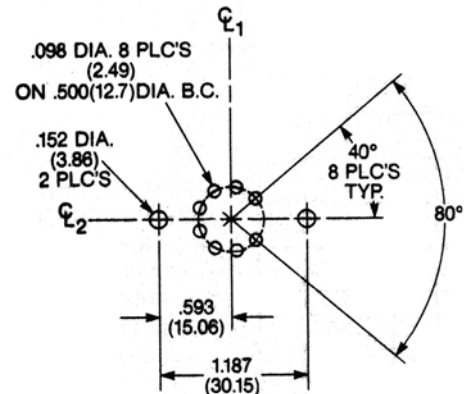
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LA000B3U	LA000B3CB	LA000B3B	Undrilled	--	10.8
LAT03B3U	LAT03B3CB	LAT03B3B	TO-3	2	10.8
LAIC3B3U	LAIC3B3CB	LAIC3B3B	TO-3 IC	4	10.8
LA407B3U	LA407B3CB	LA407B3B	TO-3 (4-pin)	5	10.8
LA394B3U	LA394B3CB	LA394B3B	Universal	8	10.8

### HOLE PATTERNS

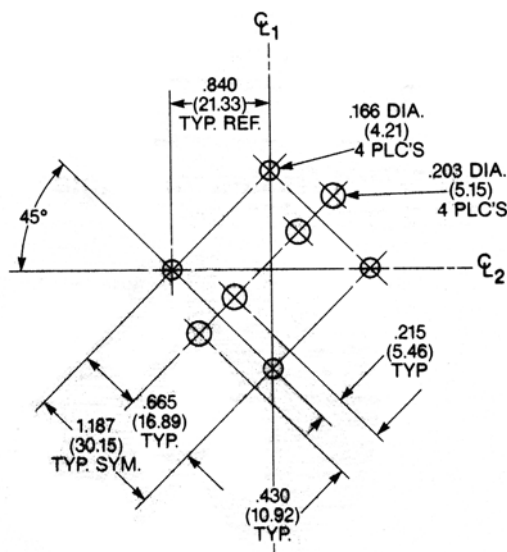
2. Hole Pattern no. 236 accommodates TO-3s. Available in LA-B series heat dissipators only.



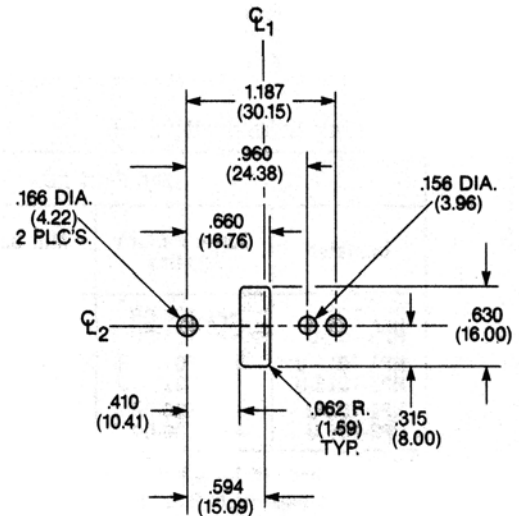
4. Hole pattern no. 237 accommodates To-3 ICs. Available in LA-B series heat dissipators only.



5. Hole pattern no. 407 accommodates TO-3s (4-pin). Available in LA-B series heat dissipators only.



8. Hole pattern no. 394 (universal) accommodates TO-3s, TO-66s, TO-126s, TO-127s, or T-220s. Available in LA-B series heat dissipators only.



### CTS IERC, Heat Sinks and Thermal Management Solutions

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